

The Perfect Wireless Interconnect

Three billion contacts in use without a single known failure.

The Challenge

Board space within the Wireless Hand Held Device Industry is always a premium. Available space to support an antenna interconnect was only 3.0mm by 1.0mm with a working height of 0.90mm. Material overstressing, component stability on the board, and achieving high hertz forces were potential concerns.

The Engineered Product Solution

Create a 300k psi interconnect contact, with a minimum of 0.5N of force, 0.60mm of deflection, and true signal integrity maintainability through the antenna path.

Innovative Interconnect Benefits

- No field failures with 3 billion contacts in the field
- Manufacturing forgiveness through 0.6mm of deflection
- Stable transmission and reception of signals due to high Hertz force design
- Reduced real estate utilization through a unique and innovative “preloaded” small footprint design

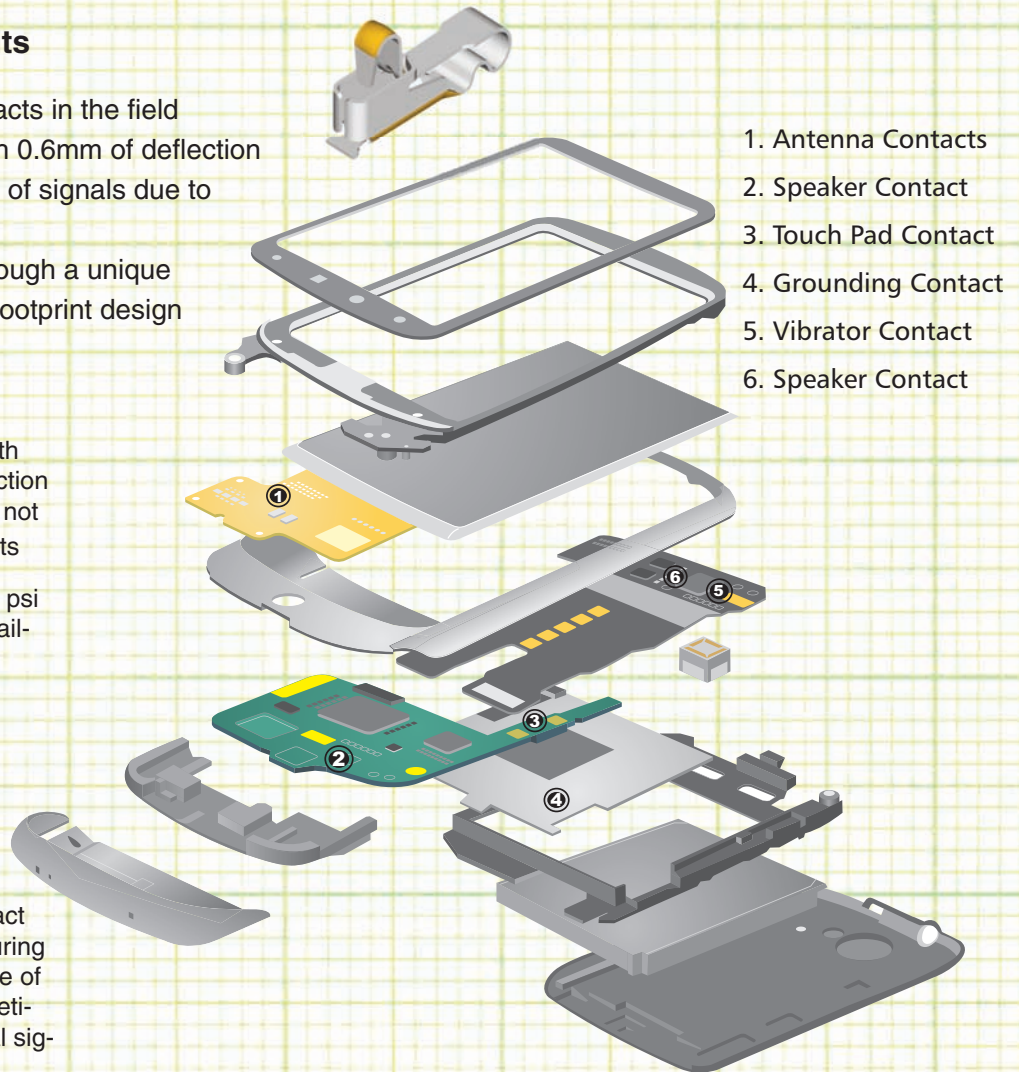
Attributes and Values

Pre-Load tabs, providing 0.3N of force with 0.1mm of deflection allowing for the reduction of end product size and weight, a feature not found on most of our competitor’s products

Innovative Dome Contact, providing 300k psi contact force and ensuring zero {0} field failures, a contact force roughly twice that of most of our competitor’s products

Solder Well, increasing customer manufacturing forgiveness through the elimination of solder wicking, a feature not found on most of our competitor’s products

BeCu or TiCu materials, providing a contact resistance of <20 milli ohms thereby ensuring clear transmission and reception. The use of stainless steel, common with some competitive products, actually produces additional signal noise and reduced operational cycles.



Applications

- Handset
- Smart Phone
- GPS Units
- Key Fob
- Set Top Boxes
- Laptop and Computers
- Smoke Detector
- Memory Stick
- CT Scan Equipment

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